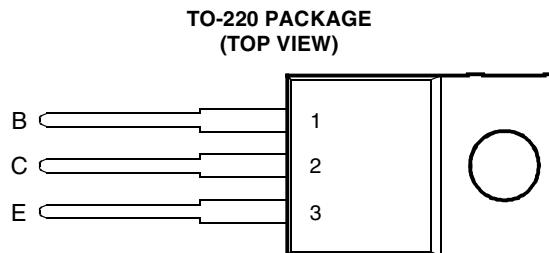


- Rugged Triple-Diffused Planar Construction
- 4 A Continuous Collector Current
- Operating Characteristics Fully Guaranteed at 100°C
- 1000 Volt Blocking Capability



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-base voltage ($I_E = 0$)	TIPL791 TIPL791A	V_{CBO}	850 1000	V
Collector-emitter voltage ($V_{BE} = 0$)	TIPL791 TIPL791A	V_{CES}	850 1000	V
Collector-emitter voltage ($I_B = 0$)	TIPL791 TIPL791A	V_{CEO}	400 450	V
Emitter-base voltage		V_{EBO}	10	V
Continuous collector current		I_C	4	A
Peak collector current (see Note 1)		I_{CM}	8	A
Continuous device dissipation at (or below) 25°C case temperature		P_{tot}	75	W
Operating junction temperature range		T_j	-65 to +150	°C
Storage temperature range		T_{stg}	-65 to +150	°C

NOTE 1: This value applies for $t_p \leq 10$ ms, duty cycle $\leq 2\%$.

PRODUCT INFORMATION

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
$V_{CEO(sus)}$	$I_C = 100 \text{ mA}$	$L = 25 \text{ mH}$	(see Note 2)	TIPL791 TIPL791A	400 450			V
I_{CES}	$V_{CE} = 850 \text{ V}$	$V_{BE} = 0$		TIPL791			5	μA
	$V_{CE} = 1000 \text{ V}$	$V_{BE} = 0$		TIPL791A			5	
	$V_{CE} = 850 \text{ V}$	$V_{BE} = 0$	$T_C = 100^\circ\text{C}$	TIPL791			200	
	$V_{CE} = 1000 \text{ V}$	$V_{BE} = 0$	$T_C = 100^\circ\text{C}$	TIPL791A			200	
I_{CEO}	$V_{CE} = 400 \text{ V}$	$I_B = 0$		TIPL791			5	μA
	$V_{CE} = 450 \text{ V}$	$I_B = 0$		TIPL791A			5	
I_{EBO}	$V_{EB} = 10 \text{ V}$	$I_C = 0$					1	mA
h_{FE}	Forward current transfer ratio	$V_{CE} = 5 \text{ V}$	$I_C = 0.5 \text{ A}$	(see Notes 3 and 4)	20		60	
$V_{CE(sat)}$	$I_B = 0.2 \text{ A}$	$I_C = 1 \text{ A}$					0.5	V
	$I_B = 0.5 \text{ A}$	$I_C = 2.5 \text{ A}$	(see Notes 3 and 4)				1.0	
	$I_B = 1 \text{ A}$	$I_C = 4 \text{ A}$					2.5	
	$I_B = 1 \text{ A}$	$I_C = 4 \text{ A}$	$T_C = 100^\circ\text{C}$				5.0	
$V_{BE(sat)}$	$I_B = 0.2 \text{ A}$	$I_C = 1 \text{ A}$					1.0	V
	$I_B = 0.5 \text{ A}$	$I_C = 2.5 \text{ A}$	(see Notes 3 and 4)				1.2	
	$I_B = 1 \text{ A}$	$I_C = 4 \text{ A}$					1.4	
	$I_B = 1 \text{ A}$	$I_C = 4 \text{ A}$	$T_C = 100^\circ\text{C}$				1.3	
f_t	Current gain bandwidth product	$V_{CE} = 10 \text{ V}$	$I_C = 0.5 \text{ A}$	$f = 1 \text{ MHz}$			12	MHz
C_{ob}	Output capacitance	$V_{CB} = 20 \text{ V}$	$I_E = 0$	$f = 0.1 \text{ MHz}$			110	pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques, $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1.66	$^\circ\text{C/W}$

inductive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]			MIN	TYP	MAX	UNIT
t_{sv}	$I_C = 4 \text{ A}$ $V_{BE(off)} = -5 \text{ V}$	$I_{B(on)} = 0.8 \text{ A}$ (see Figures 1 and 2)				2	μs
t_{rv}						200	ns
t_{fi}						100	ns
t_{ti}						50	ns
t_{xo}						200	ns
t_{sv}	$I_C = 4 \text{ A}$ $V_{BE(off)} = -5 \text{ V}$	$I_{B(on)} = 0.8 \text{ A}$ $T_C = 100^\circ\text{C}$ (see Figures 1 and 2)				2.5	μs
t_{rv}						400	ns
t_{fi}						200	ns
t_{ti}						50	ns
t_{xo}						600	ns

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PRODUCT INFORMATION

PARAMETER MEASUREMENT INFORMATION

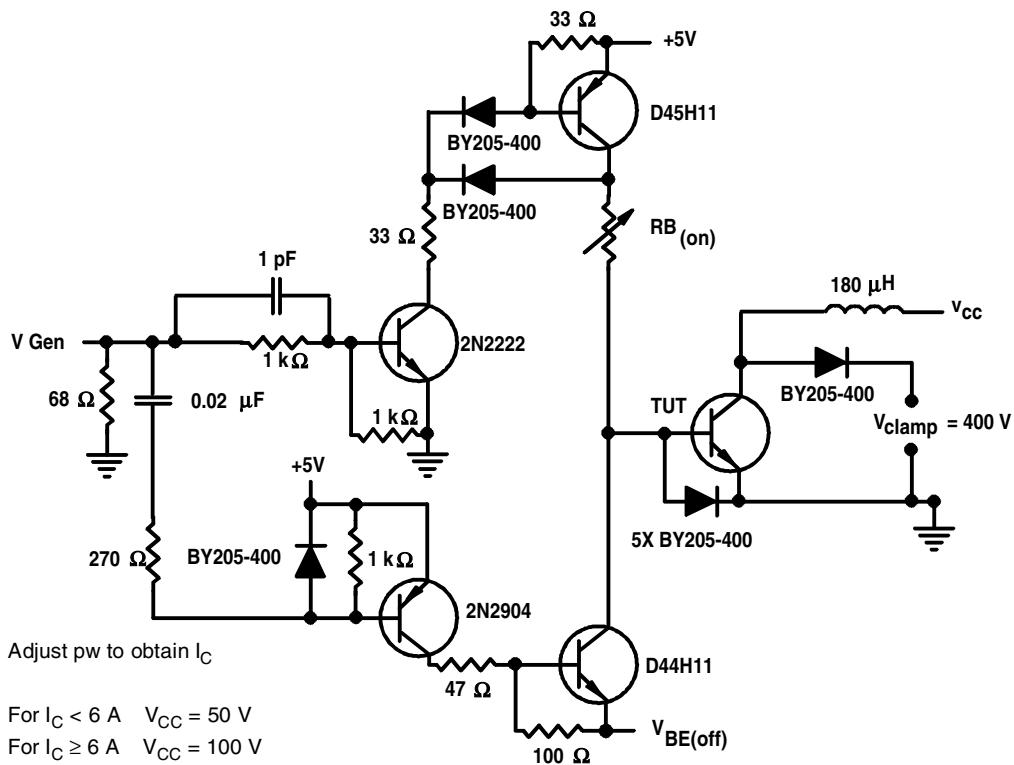
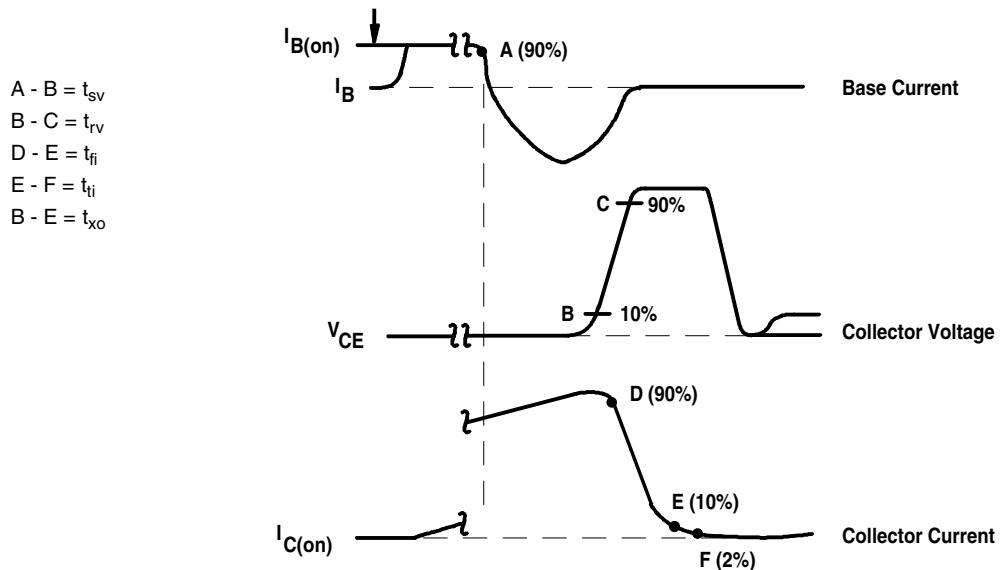


Figure 1. Inductive-Load Switching Test Circuit



NOTES: A. Waveforms are monitored on an oscilloscope with the following characteristics: $t_r < 15$ ns, $R_{in} > 10 \Omega$, $C_{in} < 11.5$ pF.
B. Resistors must be noninductive types.

Figure 2. Inductive-Load Switching Waveforms

PRODUCT INFORMATION

MAY 1989 - REVISED SEPTEMBER 2002
Specifications are subject to change without notice.

TYPICAL CHARACTERISTICS

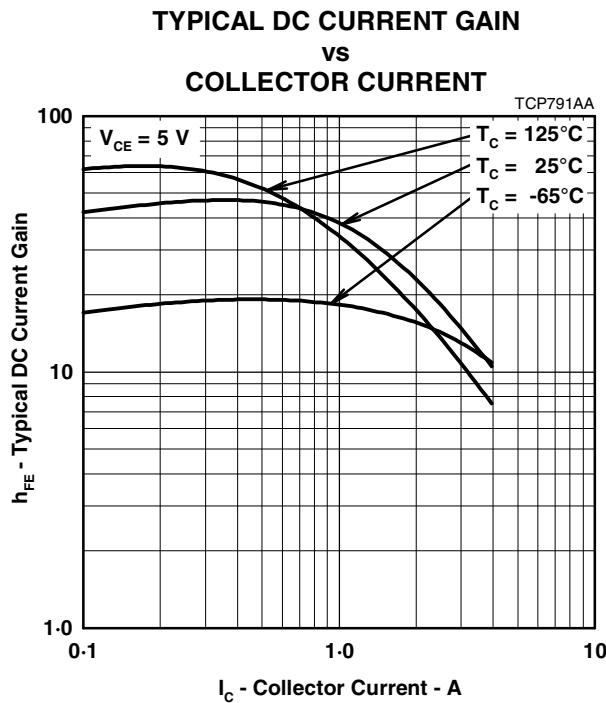


Figure 3.

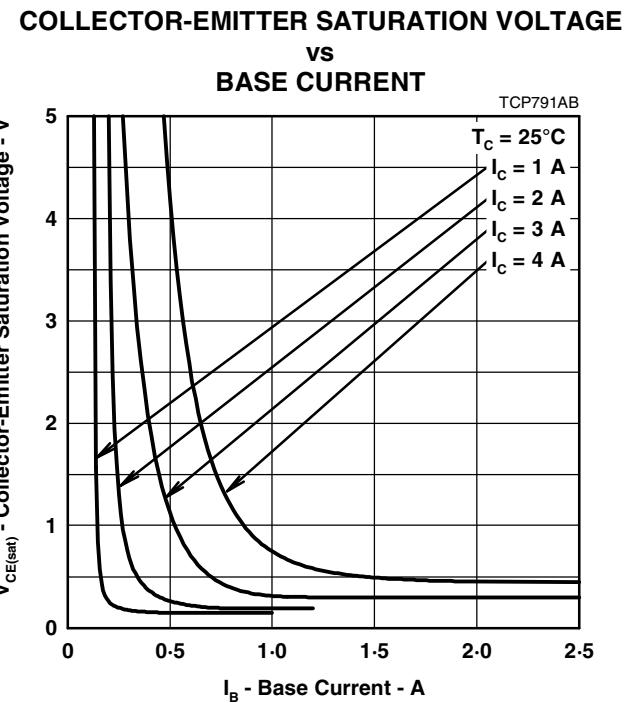


Figure 4.

MAXIMUM SAFE OPERATING REGIONS

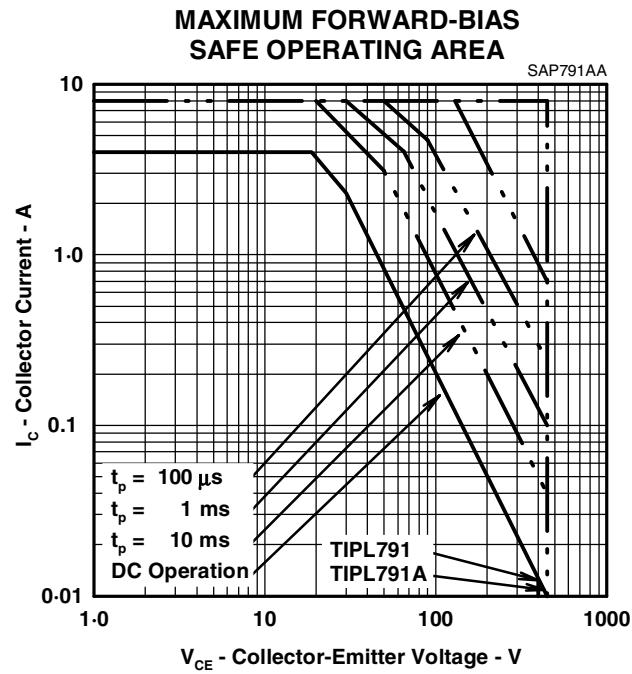


Figure 5.

PRODUCT INFORMATION

THERMAL INFORMATION

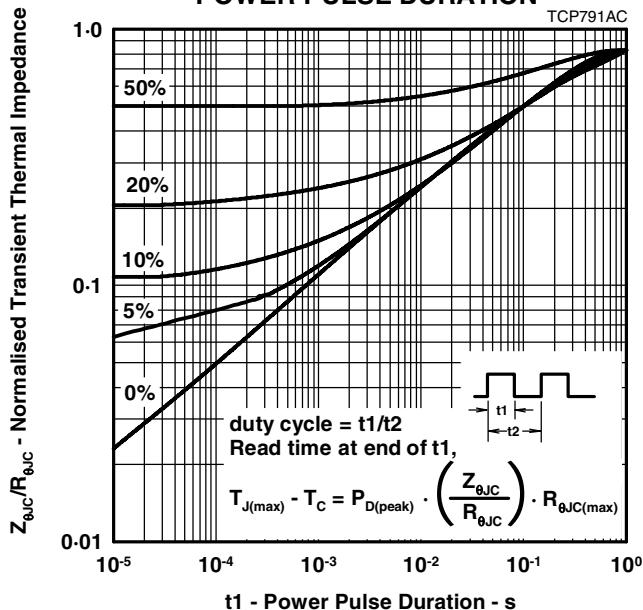
THERMAL RESPONSE JUNCTION TO CASE
VS
POWER PULSE DURATION

Figure 6.

PRODUCT INFORMATION

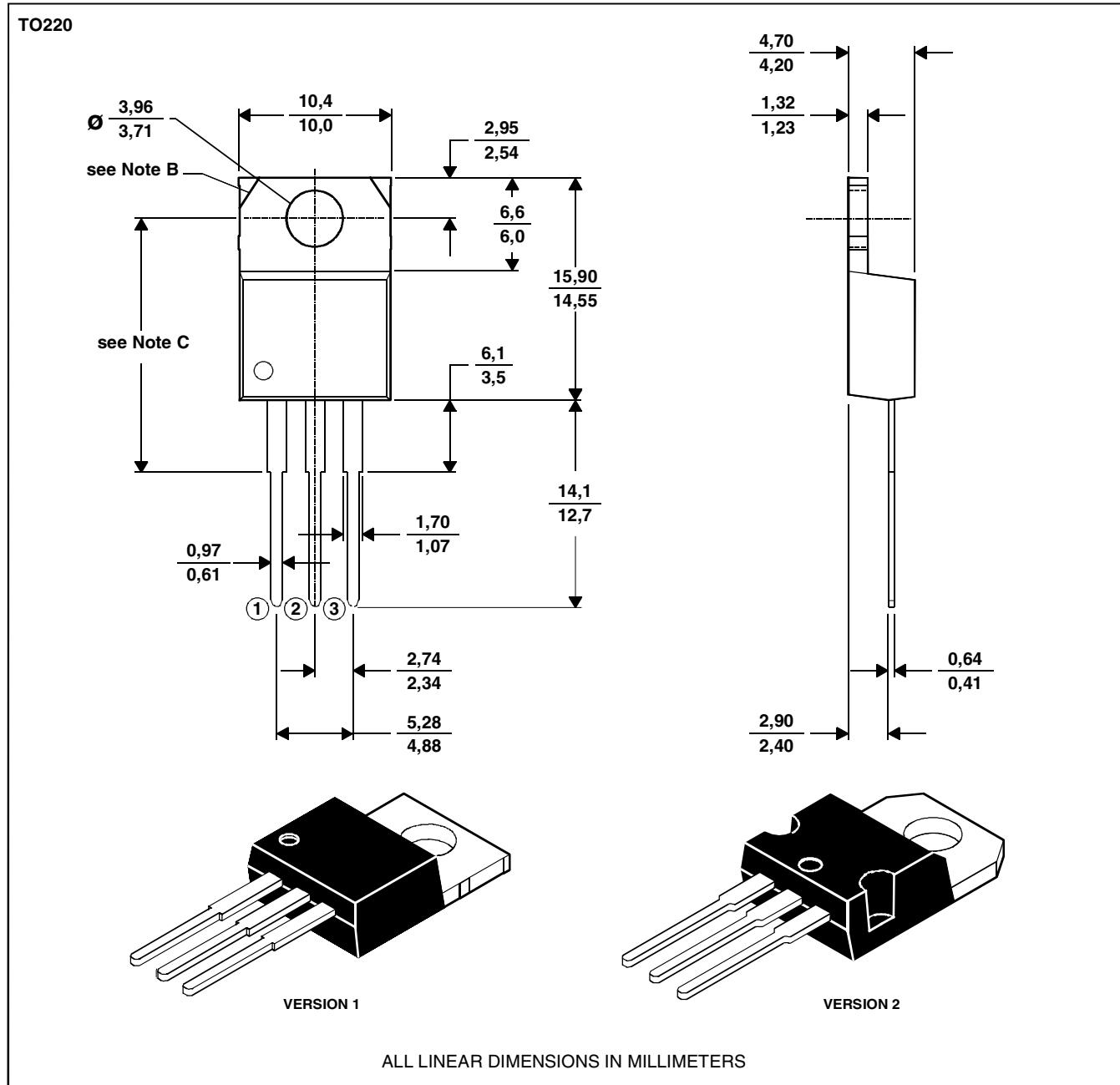
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

MDXXBE

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version.

Version 1, 18,0 mm. Version 2, 17,6 mm.

PRODUCT INFORMATION